

CONTACT PAD AND POGO PIN INTERCONNECTS

As electronic devices continue to evolve with increasing performance demands, designers require interconnect solutions that can support dependable power and signal transmission across repeated mating cycles. TE Connectivity (TE) contact pads and pogo pins are engineered to work together as board level mating interfaces, helping enable consistent electrical performance and mechanical stability in a wide range of applications. Designed for repeated contact and efficient integration, these interconnects support consistent connections in designs where durability, space efficiency, and manufacturing compatibility are important.



TARGET INDUSTRIES

- IoT & edge devices
- Consumer electronics
- Medical portable devices
- Industrial

TARGET APPLICATIONS

- Wearable devices (smart watches, earbuds, VR/AR)
- Docking and charging interfaces
- Portable device and testing measurement equipment
- Tablets, laptops, and handheld terminals
- Medical monitoring and diagnostic devices
- Smart home appliances

CONTACT PADS

TE Connectivity's contact pad offers a robust, all-metal, gold/platinum plated solution for surface-mount (SMT) applications.

Engineered for notable durability and consistent performance, these pads help address the limitations of standard copper foil, providing an enhanced mating connection. They support greater design flexibility and long-term consistency in demanding applications.



KEY BENEFITS AND FEATURES

DESIGN FLEXIBILITY

- Multiple diameters and heights to support a wide range of component layout and mechanical enclosure requirements.
- Diameters: 1.5mm, 1.63mm, 1.98mm, 2.99mm
- Heights: 0.64mm, 0.8mm, 1.14mm, 1.4mm, 1.91mm

DURABLE

- Full-metal construction with gold or platinum plating to support enhanced conductivity and oxidation resistance.
- Helps to enable stable connections compared with simple copper foil.

COMPATIBILITY

- Well-suited conductive mating surface for pogo pins, spring fingers, and test probes.

EFFICIENT ASSEMBLY

- Flat, circular shape is suitable for SMT soldering, helps to enable automated production and streamline the manufacturing process.

KEY BENEFITS AND FEATURES

Part Number	Plating	Diameter	Thickness
2511417-1	Gold	1.98mm	0.64mm
2511417-2	Gold	1.98mm	1.14mm
2511417-3	Gold	1.98mm	1.4mm
2511418-1	Gold	2.99mm	1.4mm
2511418-2	Gold	2.99mm	1.91mm
2511420-1	Gold	1.5mm	0.8mm
2528102-1	Platinum	1.63mm	0.45mm

[VIEW ALL CONTACT PAD PRODUCTS >>](#)

POGO PINS

Pogo pins are spring loaded electrical contacts designed for compact and stable electrical connection. Each pogo pin consists of a plunger, barrel, and internal spring. Key features include higher durability, more stable resistance, compact dimension, higher current capacity, and easier mating.

Pogo pins are typically used with a contact pad or a flat metal surface and are widely used in power charging and signal transmission applications.



KEY BENEFITS AND FEATURES

- Spring-loaded contact for improved electrical performance
- Rated up to 1 A per pin
- Supports up to 10,000 mating cycles
- Compact size suitable for space-constrained designs
- Available in SMT and through-hole mounting types
- Pogo pins and cable assemblies can be customized to meet customer specific requirements

STANDARD PART OFFERINGS

Part Number	Pos.	Type	Mounting Type	Plunger Plating	Plunger Dia (mm)	Uncompressed Height (mm)	Max. working height (mm)	Recommendation Working Height (mm)	Min. Working Height (mm)
2528103-1	1	Pogo Pin	Through-hole	Platinum	0.8	6.6	5.8	5.6	5.3
2528104-1	1	Pogo Pin	SMT	Gold	0.9	3	2.5	2.3	2.1
2528105-1	2	Pogo Pin Connector (with housing)	SMT	Gold	0.9	5	4.25	4	3.6
2528106-1	2	Pogo Pin Connector (with housing)	Through-hole	Gold	0.9	5.5	4.75	4.5	4.1

[VIEW ALL POGO PIN PRODUCTS >>](#)

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